

# HM6709 Series — Preliminary

T-46-23-10

65536-Word × 4-Bit High Speed Static RAM (with  $\overline{OE}$ )

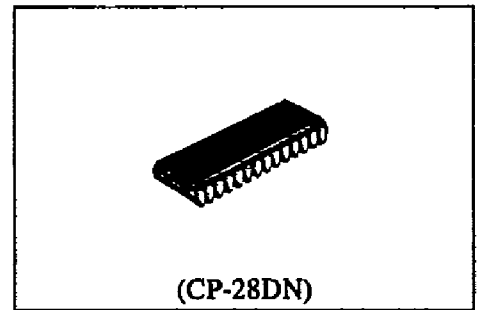
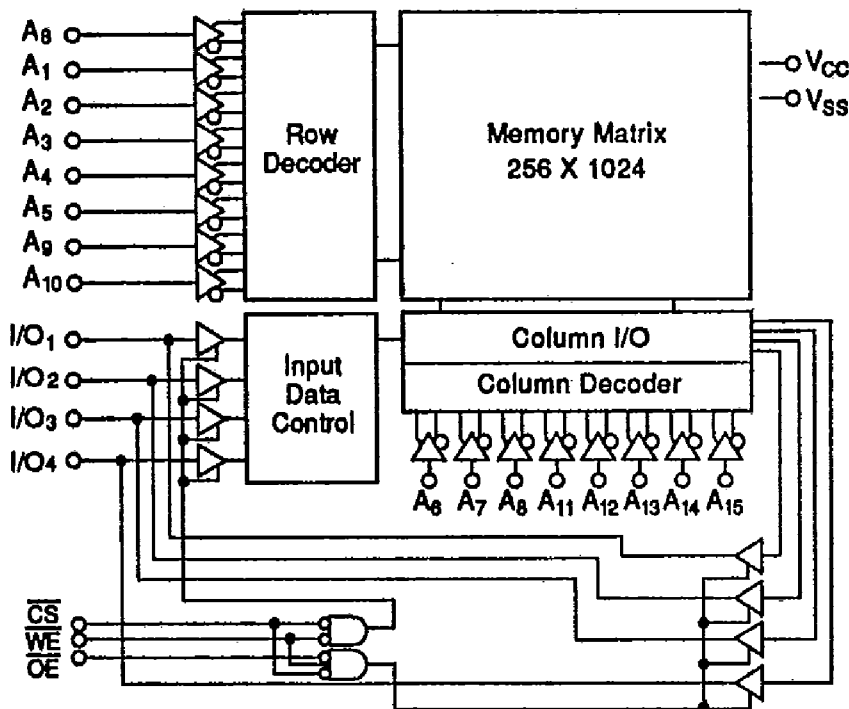
## ■ FEATURES

- Super Fast  
Access Time .....20/25ns (max.)
- Fast  $\overline{OE}$   
Access Time .....10ns (max.)
- Low Power Dissipation .....350mW (typ.)
- +5V Single Supply
- Completely Static Memory  
No Clock or Timing Strobe Required
- Balanced Read and Write Cycle Time
- Fully TTL Compatible Input and Output
- 300 mil 28 pin SOJ

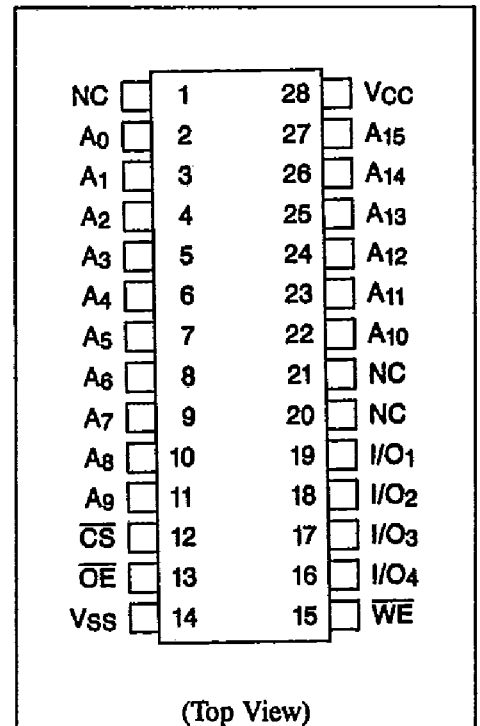
## ■ ORDERING INFORMATION

Type No.	Access Time	Package
HM6709JP-20	20ns	300 mil 28 pin
HM6709JP-25	25ns	Plastic SOJ (CP-28DN)

## ■ BLOCK DIAGRAM



## ■ PIN ARRANGEMENT



### ■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Rating	Unit
Terminal Voltage to $V_{SS}$ Pin	$V_T$	-0.5 to +7.0	V
Power Dissipation	$P_T$	1.0	W
Operating Temperature Range	$T_{opr}$	0 to +70	°C
Storage Temperature Range (with bias)	$T_{stg(bias)}$	-10 to +85	°C
Storage Temperature Range	$T_{stg}$	-55 to +125	°C

### ■ RECOMMENDED DC OPERATING CONDITIONS ( $0^\circ\text{C} \leq T_a \leq 70^\circ\text{C}$ )

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	$V_{CC}$	4.5	5.0	5.5	V
	$V_{SS}$	0.0	0.0	0.0	V
Input High Voltage	$V_{IH}$	2.2	—	6.0	V
Input Low Voltage	$V_{IL}^*$	-3.0	—	0.8	V

\*Pulse width: 20ns, DC: -0.5V

### ■ TRUTH TABLE

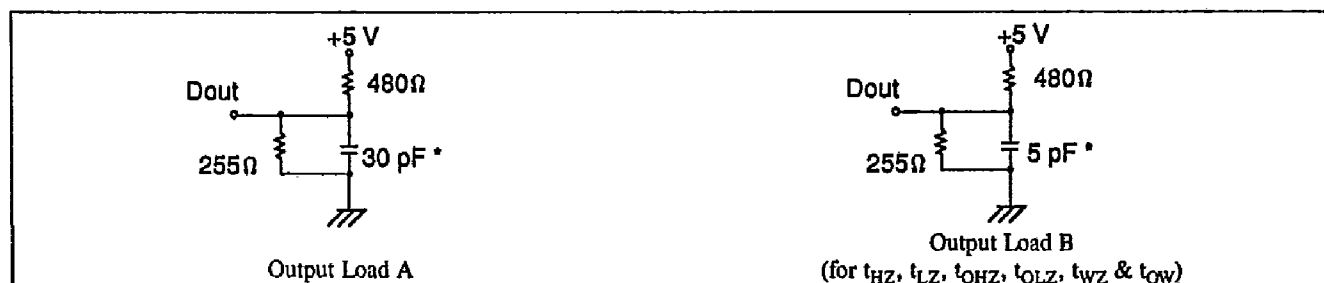
$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	$V_{CC}$ Current	I/O Pin	Ref. Cycle
H	H or L	H or L	Not Selected	$I_{SB}, I_{SB1}$	High Z	—
L	H	H	Output Disabled	$I_{CC}, I_{CC1}$	High Z	—
L	L	H	Read	$I_{CC}, I_{CC1}$	Data Out	Read Cycle (1) (2) (3)
L	H	L	Write	$I_{CC}, I_{CC1}$	Data In	Write Cycle (1) (2) (3) (4)
L	L	L		$I_{CC}, I_{CC1}$	Data In	Write Cycle (5) (6)

### ■ DC AND OPERATING CHARACTERISTICS ( $V_{CC} = 5V \pm 10\%$ , $T_a = 0^\circ\text{C}$ to $70^\circ\text{C}$ )

Item	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input Leakage Current	$ I_{LI} $	$V_{CC} = 5.5V, V_{IN} = V_{SS}$ to $V_{CC}$	—	—	2	$\mu\text{A}$
Output Leakage Current	$ I_{LO} $	$\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}, \overline{WE} = V_{IL}$ $V_{I/O} = V_{SS}$ to $V_{CC}$	—	—	10	$\mu\text{A}$
Operating Power Supply Current	$I_{CC}$	$\overline{CS} = V_{IL}, I_{I/O} = 0\text{mA}$	—	—	100	mA
Average Operating Current	$I_{CC1}$	Min. Cycle, Duty: 100%, $I_{I/O} = 0\text{mA}$	—	—	120	mA
Standby Power Supply Current	$I_{SB}$	$\overline{CS} = V_{IH}, V_{IN} = V_{IH}$ or $V_{IL}$	—	—	30	mA
	$I_{SB1}$	$\overline{CS} \geq V_{CC} - 0.2V$ $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$	—	—	10	mA
Output Low Voltage	$V_{OL}$	$I_{OL} = 8\text{mA}$	—	—	0.4	V
Output High Voltage	$V_{OH}$	$I_{OH} = -4\text{mA}$	2.4	—	—	V

### ■ AC TEST CONDITIONS

- Input Pulse Levels:  $V_{SS}$  to 3.0V
- Input and Output Reference Levels: 1.5V
- Input Rise and Fall Time: 4ns
- Output Load: See Figure



\*Including scope and jig capacitance.



**■ CAPACITANCE** ( $T_a = 25^\circ\text{C}$ ,  $f = 1.0\text{MHz}$ )

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input Capacitance	$C_{IN}$	$V_{IN} = 0\text{V}$	—	—	6	pF
Input/Output Capacitance	$C_{I/O}$	$V_{I/O} = 0\text{V}$	—	—	10	pF

**NOTE:** This parameter is sampled and not 100% tested.

**■ AC CHARACTERISTICS** ( $V_{CC} = 5\text{V} \pm 10\%$ ,  $T_a = 0^\circ\text{C}$  to  $70^\circ\text{C}$ , unless otherwise noted.)

**• Read Cycle**

Item	Symbol	HM6709JP-20		HM6709JP-25		Unit	Notes
		Min.	Max.	Min.	Max.		
Read Cycle Time	$t_{RC}$	20	—	25	—	ns	—
Address Access Time	$t_{AA}$	—	20	—	25	ns	—
Chip Select Access Time	$t_{ACS}$	—	20	—	25	ns	—
Chip Selection to Output in Low Z	$t_{LZ}$	0	—	0	—	ns	1, 2
Output Enable to Output Valid	$t_{OE}$	0	10	0	10	ns	—
Output Enable to Output in Low Z	$t_{OLZ}$	0	—	0	—	ns	1, 2
Chip Deselection to Output in High Z	$t_{HZ}$	0	8	0	10	ns	1, 2
Output Hold from Address Change	$t_{OH}$	5	—	5	—	ns	—

**NOTES:** 1. This parameter is sampled and not 100% tested.  
2. Transition is measured  $\pm 200\text{mV}$  from steady state voltage with specified loading is Load B.

**• Write Cycle**

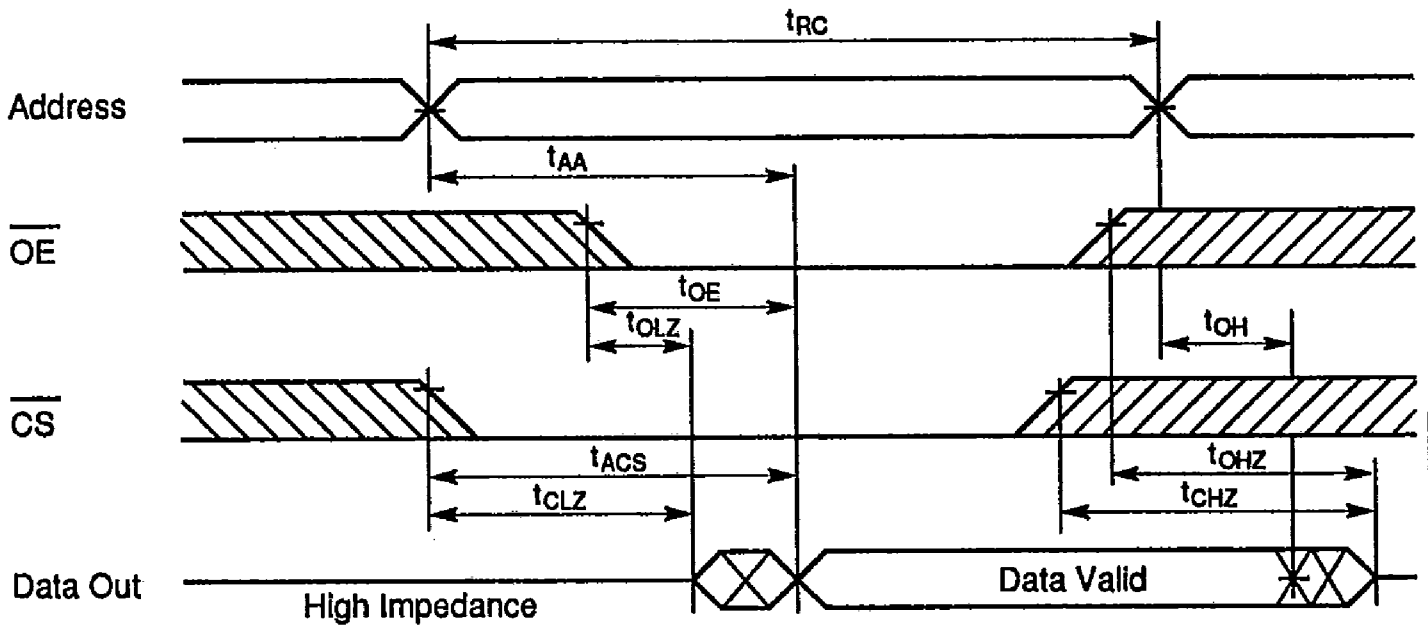
Item	Symbol	HM6709JP-20		HM6709JP-25		Unit	Notes
		Min.	Max.	Min.	Max.		
Write Cycle Time	$t_{WC}$	20	—	25	—	ns	1
Chip Selection to End of Write	$t_{CW}$	15	—	20	—	ns	—
Address Setup Time	$t_{AS}$	0	—	0	—	ns	—
Address Valid to End of Write	$t_{AW}$	15	—	20	—	ns	—
Write Pulse Width	$t_{WP}$	15	—	20	—	ns	—
Write Recovery Time	$t_{WR}$	3	—	3	—	ns	—
Write to Output in High Z	$t_{WZ}$	0	8	0	10	ns	2, 3
Data Valid to End of Write	$t_{DW}$	12	—	15	—	ns	—
Data Hold Time	$t_{DH}$	0	—	0	—	ns	—
Output Disable to Output in High Z	$t_{OHZ}$	0	8	0	10	ns	2, 3
Output Active from End of Write	$t_{OW}$	0	—	0	—	ns	2, 3

**NOTES:** 1. All write cycle timings are referenced from the last valid address to the first transitioning address.  
2. This parameter is sampled and not 100% tested.  
3. Transition is measured  $\pm 200\text{mV}$  from steady state voltage with specified loading in Load B.

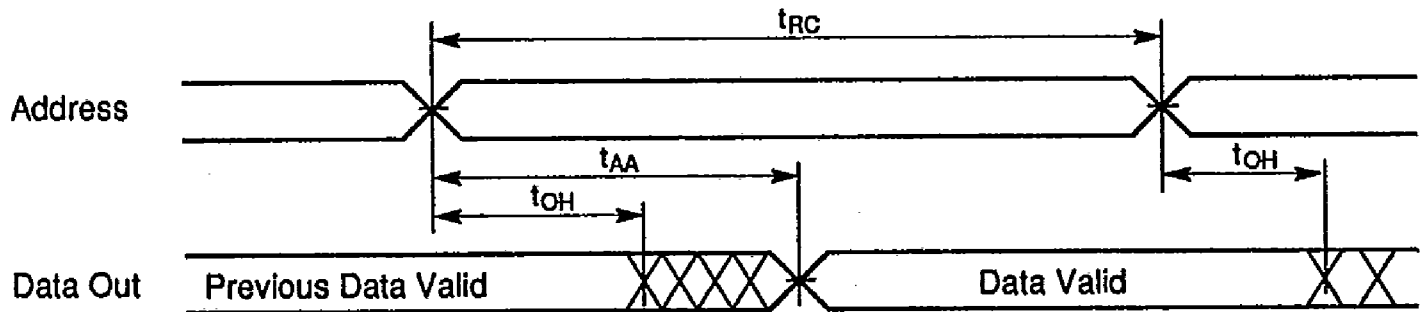
■ TIMING WAVEFORM

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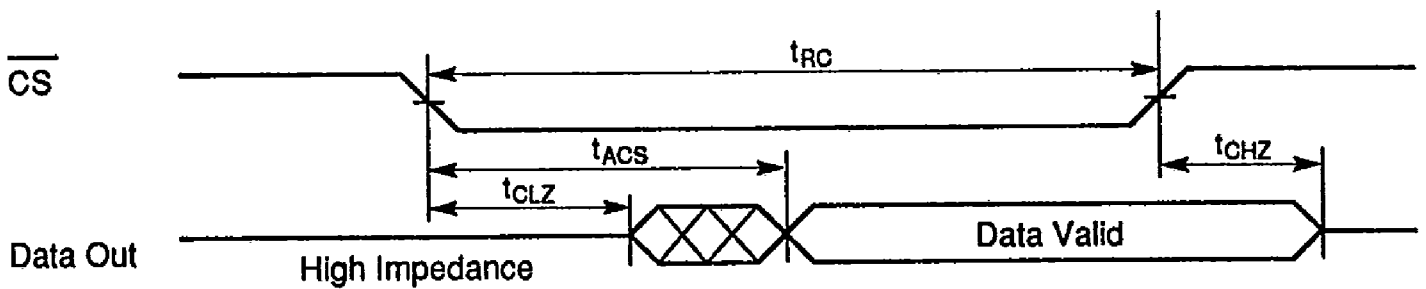
• Read Cycle (1) (1)



• Read Cycle (2) (1) (2) (3)

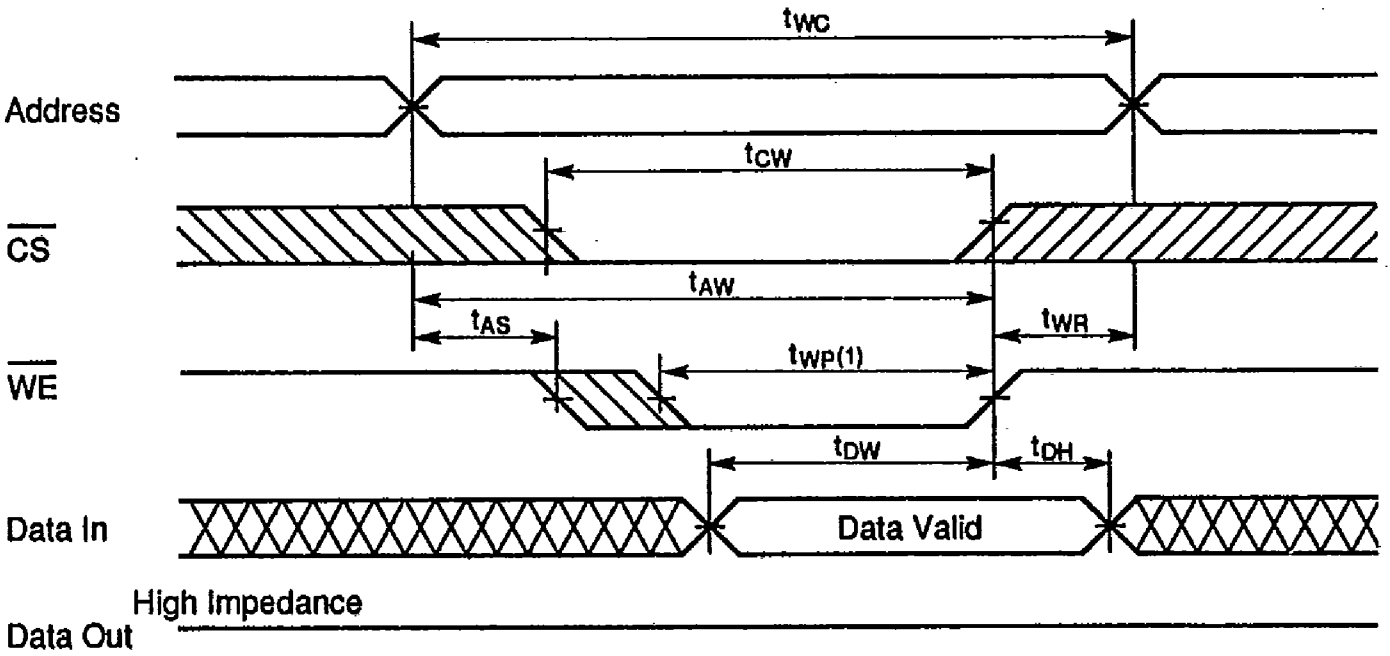


• Read Cycle (3) (1) (3) (4)

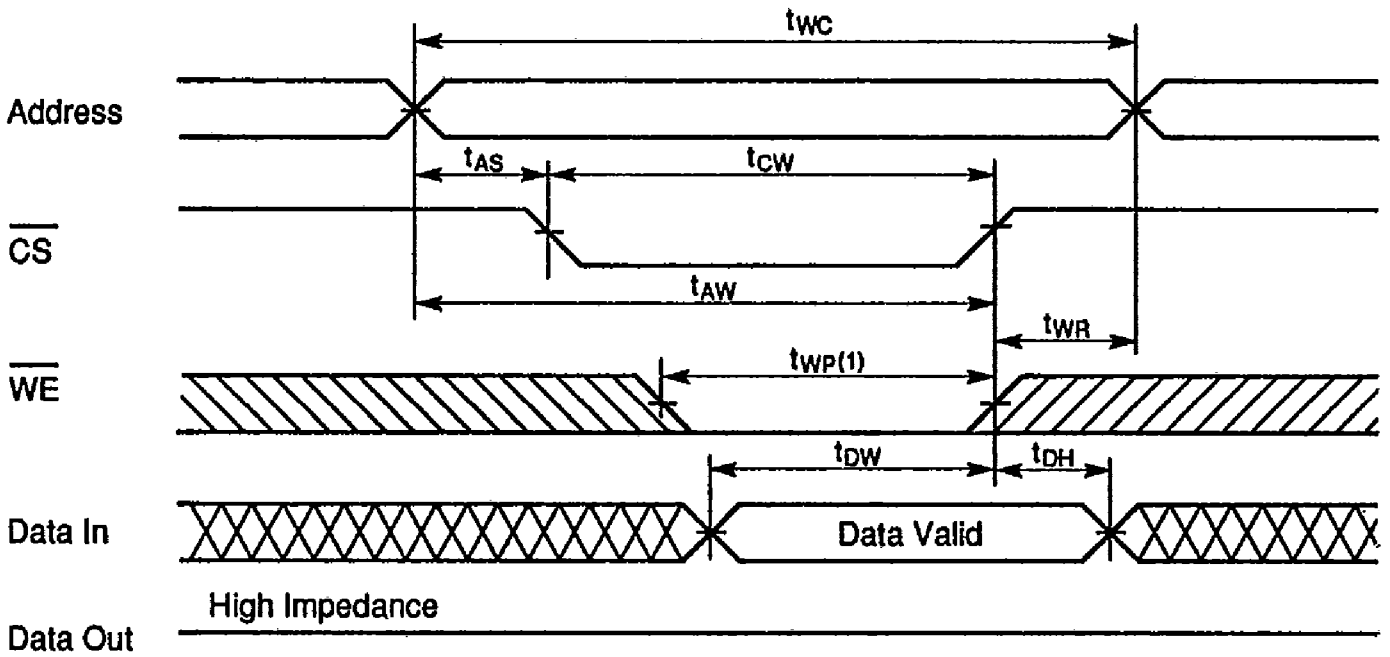


- NOTES:
1.  $\overline{WE} = V_{IH}$
  2.  $\overline{CS} = V_{IL}$
  3.  $\overline{OE} = V_{IL}$
  4. Address valid prior to or coincident with  $\overline{CS}$  transition low.

• Write Cycle (1) ( $\overline{OE} = H, \overline{WE}$  Controlled)

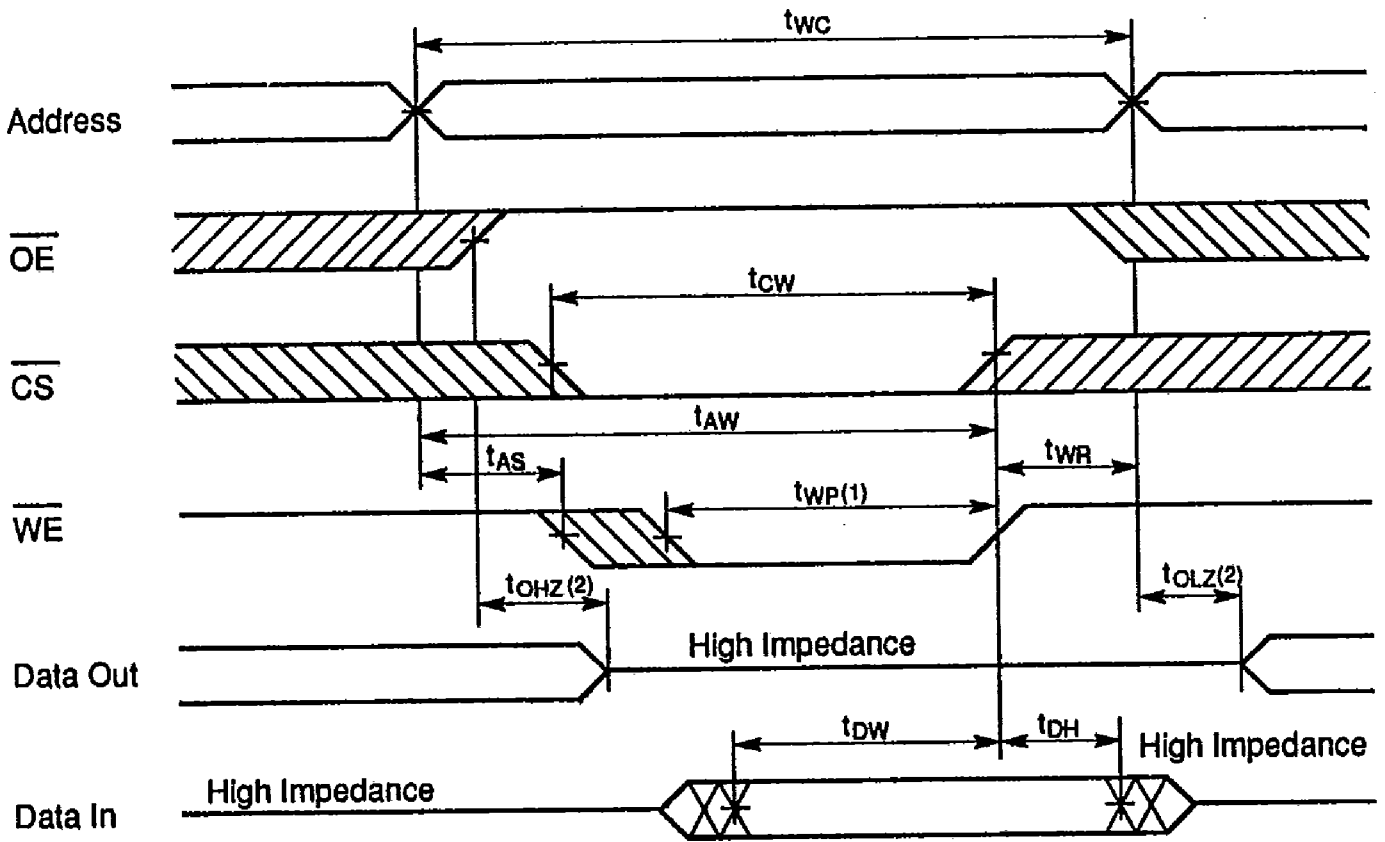


• Write Cycle (2) ( $\overline{OE} = H, \overline{CS}$  Controlled)

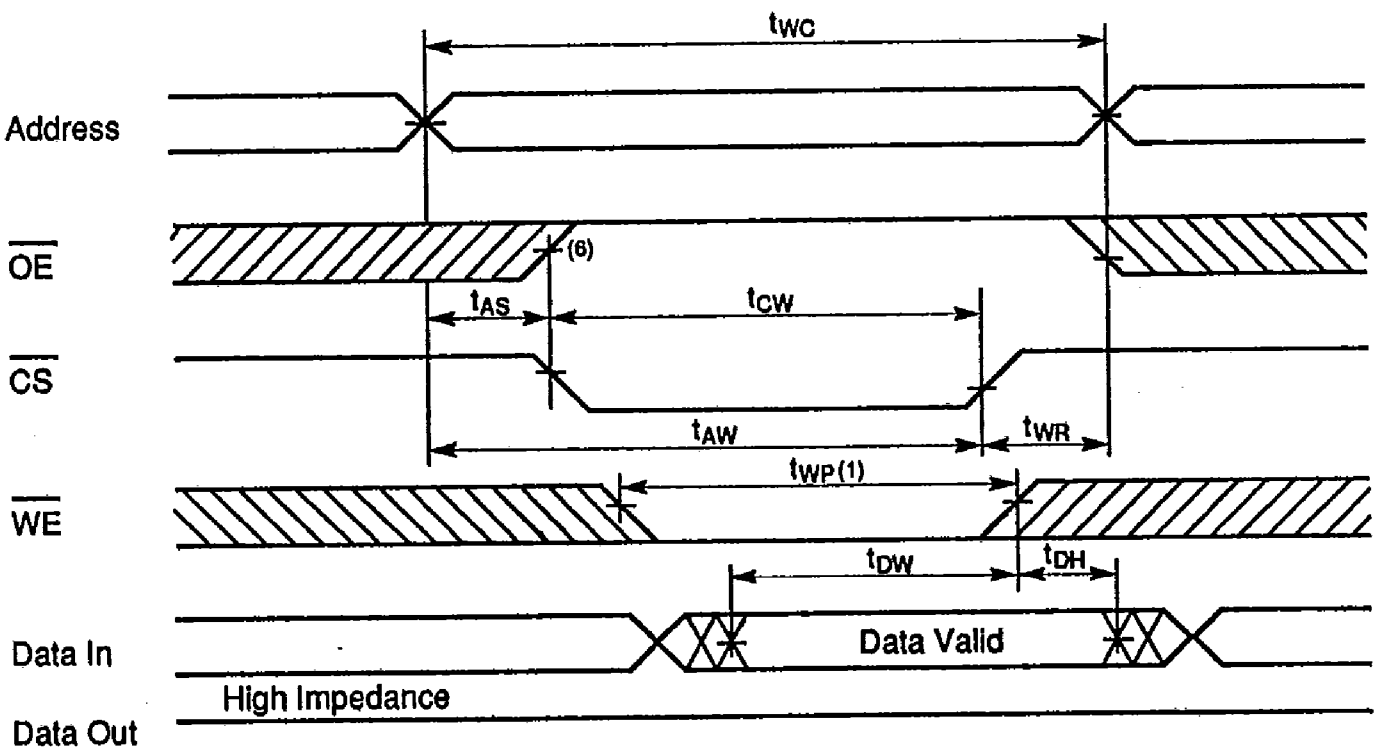


• Write Cycle (3) ( $\overline{OE}$  = Clocked,  $\overline{WE}$  Controlled)

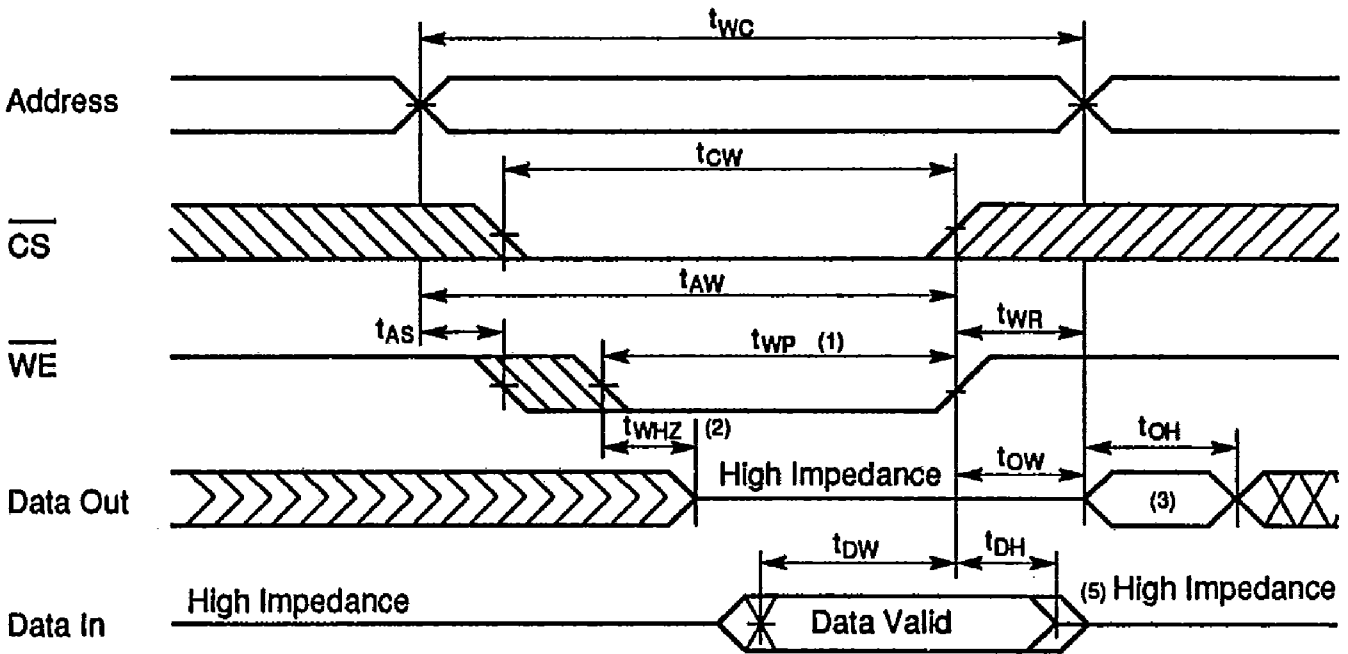
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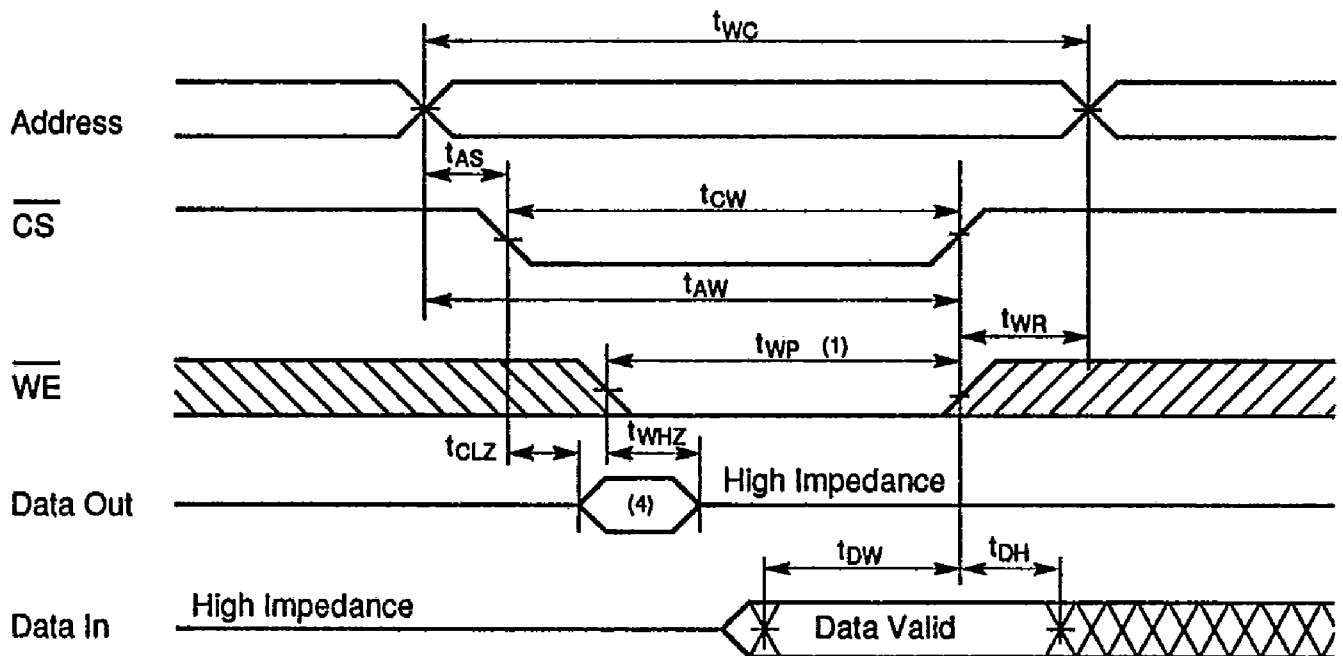
• Write Cycle (4) ( $\overline{OE}$  = Clocked,  $\overline{CS}$  Controlled)



• Write Cycle (5) ( $\overline{OE} = L, \overline{WE}$  Controlled)



• Write Cycle (6) ( $\overline{OE} = L, \overline{CS}$  Controlled)



NOTES:

1. A write occurs during the overlap ( $t_{WP}$ ) of a low  $\overline{CS}$  and a low  $\overline{WE}$ .
2. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
3. Output data is the same phase of write data of this write cycle.
4. If the  $\overline{CS}$  is low transition occurs after the  $\overline{WE}$  low transition, output remain in a high impedance state.
5. If  $\overline{CS}$  is low during this period, I/O pins are in the output state. Then, the data input signals of opposite phase to the outputs must not be applied to them.
6. If  $\overline{CS}$  low transition occurs simultaneously with the  $\overline{OE}$  high transition or after the  $\overline{OE}$  transition, output remain in high impedance state.

